









PRODUCT DATASHEET



- ► PLCC6 SMD
- ➤ 5050 1.8t Series
- ► Red / Green / Blue

N0M18S28



5050 1.8t Series





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APPLICATIONS:

- **Decoration Lighting**
- Light Strip
- Display
- **Commercial Lighting**

FEATURES (Red/Green/Blue*):

- Package: PLCC6 RGB White SMD Package
- Forward Current: 20/20/20mA **Forward Voltage (typ.):** 2.0/3.3/3.2V
- Luminous Flux (typ.): 160/1000/160mcd@20mA
- Colour: Red/Green/Blue
- **CCT/Wavelength:** 530/520/465nm
- Viewing angle: 120/120/120°
- **Materials:**
 - Die: AlGaInP/InGaN/InGaN Resin: Silicone (White Diffused)
- Operating Temperature: -40~+80°C
- Storage Temperature: -40~+85°C
- **Grouping parameters:**
 - Forward voltage
 - Luminous intensity
 - **Dominant Wavelength**
- Soldering methods: IR Reflow soldering
- Preconditioning: MSL 3 according to JEDEC
- Packing: 12mm tape with 3000pcs/reel, Ø180mm (7")



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I _F	30/30/30*	mA
Pulse Forward Current (duty 1/10; width 0.1ms)	I _{MAX}	125	mA
Power Dissipation	P _D	75/111/111	mW
Reverse Voltage	V _R	-5	V
Reverse Current @5V	I _R	10	μΑ
Operating Temperature	T_OPR	-40~+80	°C
Storage Temperature	T_{STG}	-40~+85	°C

^{1. *} In the order of Red/Green/Blue.



Electrical & Optical Characteristics (Ta=25°C)

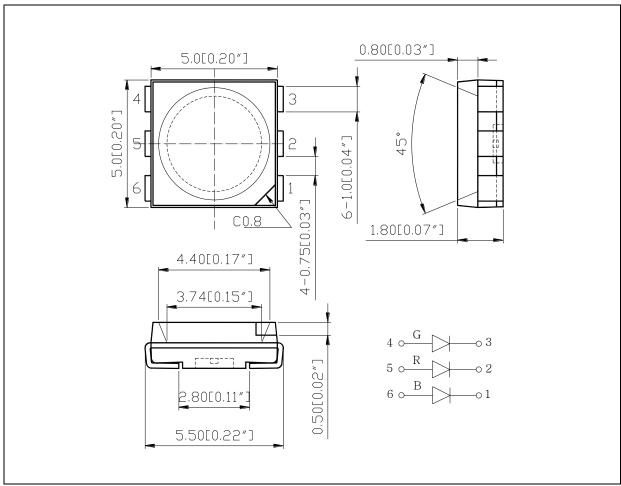
Parameter	Symbol Values		Unit	Test		
T di diffice:	3,111301	Min.	Тур.	Max.	Offic	Condition
Red - Forward Voltage	V _F	1.7	2.0	2.5	V	I _F =20mA
Red - Luminous Intensity	I _V	80	160	250	mcd	I _F =20mA
Red - Wavelength	W _D	625	630	635	nm	I _F =20mA
Red - Peak Wavelength	W _P		640		nm	I _F =20mA
Red - Spectral Half Bandwidth	Δλ		18		nm	I _F =20mA
Green - Forward Voltage	V _F	2.8	3.2	3.7	V	I _F =20mA
Green - Luminous Intensity	I _V	630	1000	1600	mcd	I _F =20mA
Green - Wavelength	W _P	515	520	525	nm	I _F =20mA
Green - Peak Wavelength	W _P		515		nm	I _F =20mA
Green - Spectral Half Bandwidth	Δλ		34		nm	I _F =20mA
Blue - Forward Voltage	V _F	2.8	3.2	3.7	V	I _F =20mA
Blue - Luminous Intensity	I _V	80	160	250	mcd	I _F =20mA
Blue - Wavelength	W _P	460	465	470	nm	I _F =20mA
Blue - Peak Wavelength	W _P		460		nm	I _F =20mA
Blue - Spectral Half Bandwidth	Δλ		26		nm	I _F =20mA
Viewing Angle	2θ _{1/2}		120		deg	I _F =20mA

^{1.} Luminous intensity (I_V) ±5%, Forward Voltage (V_F) ±0.1V



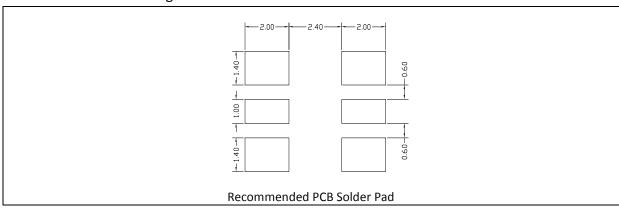
OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm with angle tolerance ±0.5°.



BINNING GROUPS:

Forward Voltage Classifications (I_F = 20mA):

Code	Min.	Max.	Unit
R	1.7	2.5	
GF / BF	2.8	3.1	V
GG / BG	3.1	3.4	V
GH / BH	3.4	3.7	

Luminous Intensity Classifications ($I_F = 20 \text{mA}$):

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Euminous intensity Classifications ($I_F = 20$ mA):				
Co	ode	Min.	Max.	Unit
	1	80	100	
	J	100	125	
Red	К	125	160	mcd
	L	160	200	
	М	200	250	
	R	630	800	
Green	S	800	1000	mcd
Green	Т	1000	1250	IIICu
	U	1250	1600	
	I	80	100	
	J	100	125	
Blue	К	125	160	mcd

160

200

200

250



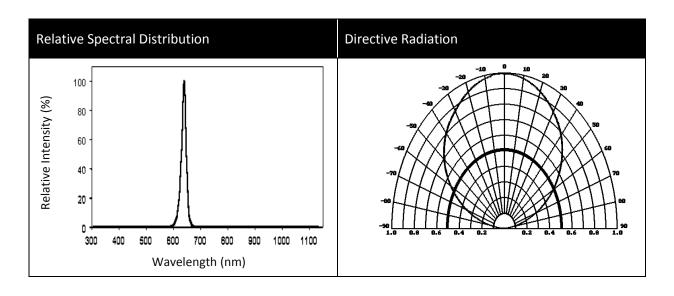
BINNING GROUPS:

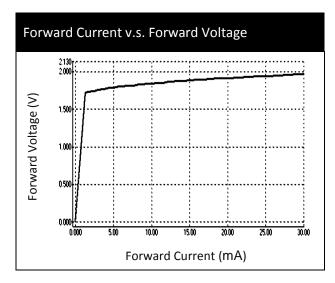
Wavelength Classifications ($I_F = 20mA$):

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Code		Min.	Max.	Unit
Red	U	625	630	200
Reu	V	630	635	nm
	S	515	517.5	nm
Green	Т	517.5	520	
	U	520	522.5	
	V	522.5	525	
Blue	E	460	462.5	nm
	F	462.5	465	
	G	465	467.5	nm
	Н	467.5	470	_



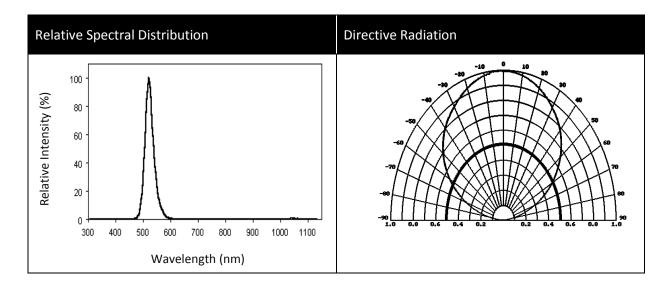
ELECTRO-OPTICAL CHARACTERISTICS (RED):

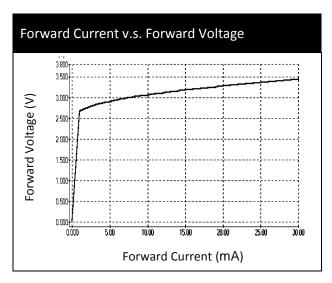






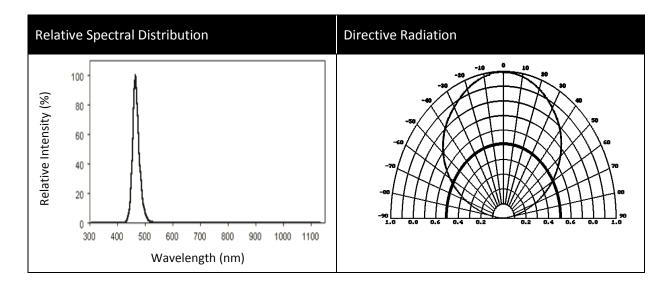
ELECTRO-OPTICAL CHARACTERISTICS (GREEN):

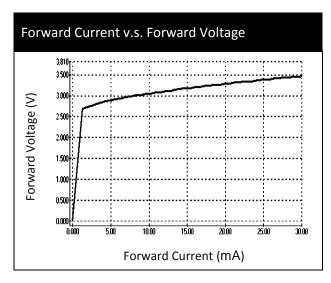






ELECTRO-OPTICAL CHARACTERISTICS (BLUE):

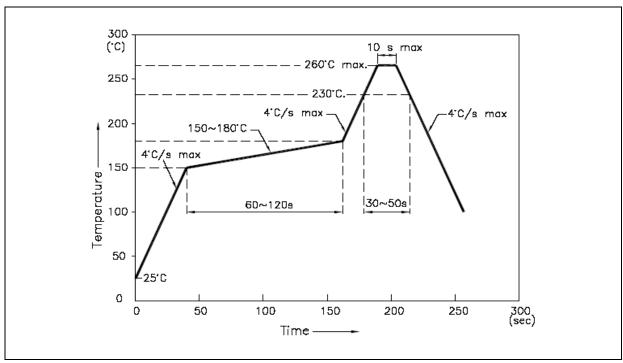






RECOMMENDED SOLDERING PROFILE:

Lead-free Solder:



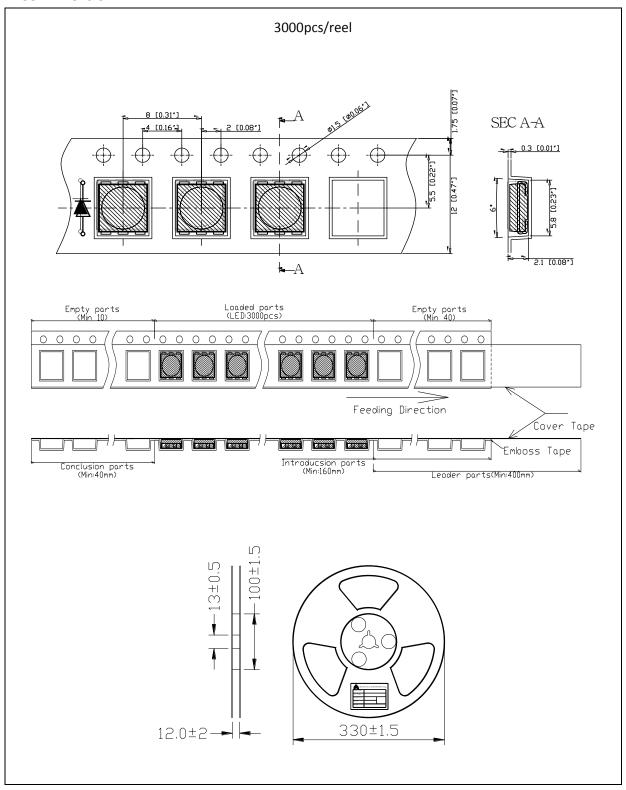
Note:

- 1. Maximum reflow soldering: 3 times.
- 2. Recommended soldering temperature 245°C; maximum soldering temperature is 260°C.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 month at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent and apply baking at 60°C±5°C for 15hrs before use.

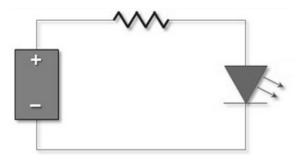
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 70±3°C x 24hrs and <5%RH, taped / reel package.
- 100±3°C x 2hrs, bulk (loose) package.
- 130±3°C x 30min, bulk (loose) package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	03/03/2016	Datasheet set-up.